EDSFair2011 Nov. Exhibition Categories of Products to be Exhibited

1 Hardware solutions
- System LSI
- ASIC / ASSP
- MPU / MCU / DSP
- FPGA / PLD
- Others

2 Hardware development (EDA)

i. IC design tools
- System level design (higher than RTL)
- Logic design (RTL to net list)
- Logic verification
- Analog design / verification
- Physical implementation
- Physical verification / analysis
- Signal integrity analysis
- Test (DFT / BIST / ATPG / others)
- DFM (OPC / RET / PSM / LRC / CAD / others)
- ASIC Prototyping
- Others

ii. PCB / SIP design tools
- Schematic capture
- Analog design / verification
- Layout
- Signal Integrity / Power Integrity / EMC analysis
- Electromagnetic field analysis
- Thermal analysis
- Others

3 Software solutions
- Embedded OS
- Device drivers
- Firmware
- Middleware
- Virtual platform / Development
- Others

4 IC tester / analyzer
- IC testers
- PCB testers
- Analyzers
- Others

5 IP core, Macro, Cell libraries

6 Embedded processor development environments
- Reconfigurable processors
- ICE
- Debuggers
- Microcomputer CASE
- Compilers / Cross Compliers
- Simulators
- Hardware / Software co-design environments
- Others

7 Design service-related (LSI / PCB)
- Design houses
- Design services
- Design consulting,
- Prototyping / Manufacturing
- IP distribution services
- Others

8 Design infrastructure (WS / PC, Network)

9 Design data management tool
- Design data management
- Others

10 Mask shop, Foundry

11 University (R&D), Consortium

12 PR-related
- Publications
- Others

Exhibitor Seminars Categories

*may slightly change due to the number of applications

- **(A) ESL** (including early SW development and virtual / HW prototyping)
- **(B) Low Power**
- **(C) Timing convergence**
- **(D) DFM**
- **(E) Reliability** (Power integrity)
- **(F) AMS design / verification**
- **(G) Functional verification** (including HW prototyping)
- **(H) IP**
- **(I) PCB**
- **(J) SIP**
- **(K) DFT**
- **(L) Physical verification**
- **(M) Physical implementation**
- **(N) Design / Verification service**
- **(O) Thermal / Fluid analysis**
- **(P) Others**

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Exhibition Application Form

How to Apply

Please read the EDSFair 2011 Nov. Exhibition Regulations.
Fill in the required information on the application form, sign it and send it to the Show Management Office at (see below).

Send to:

Japan Electronics Show Association

12F Ote Center Bldg., 1-1-3 Otemachi,
Chiyoda-ku, Tokyo 100-0004, Japan
TEL: 81-3-6212-5231 FAX:81-3-6212-5225
E-mail: info2011@edsfair.com

November 16-18, 2011

Pacifico Yokohama, Japan

Sponsor: JEITA Japan Electronics and Information Technology Industries Association

www.edsfair.com/e/

Concurrently held event : Embedded Technology 2011

TO Japan Electronics Show Association

Our company / organization will comply with all exhibition rules and regulations stipulated by both the Organizing Committee and Japan Electronics Show Association. In accordance with this agreement, we herewith submit the EDSFair 2011 Nov. Exhibition Application.

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EDSFair 2011 Nov. Exhibition Application Form

Application deadline	**Thursday, June 30, 2011**
Date received	

For official use only

Confirmation	Recipient No.	Member	Entry Date	Invoice	Booth No.

Our company is a

Item marked with an asterisk (※) must be filled in.

※

☐ Previous EDSFair exhibitor ☐ First-time exhibitor (Please submit company profile and product catalogs.)

☐ Member of the Japan Electronics Show Association (JESA) ☐ Non-Member

Number of Booths applied for

※

Booth Configuration	Number applied for	Exhibition fee (tax included)	
☐ 1 row (1,2,3,4,5,6)	booth(s)	1 to 3 booth (s) @¥451,500 (General exhibitors fee) @¥399,000 (JESA member fee) 4 or more booths @¥430,500 (General exhibitors fee) @¥378,000 (JESA member fee) Special fees for EDSFair2011Jan. exhibitors These special fees apply to only up to the same number of booth you exhibited at EDSFair2011 held in January. @¥294,000 (General exhibitors fee) @¥262,500 (JESA member fee)	= ¥
☐ 2 rows (4,6,8,10,12)			
☐ 3 rows (9,12,15,18)			
☐ 4 rows (16)			
☐ Block format (20,25,30,35,40,45,50)			
☐ Emarging Company Packaged Booth	booth(s)	@¥252,000	= ¥

Exhibition Categories of Products to be Exhibited

Refer to Exhibition Categories of Products to be Exhibited on the reverse side and check all that apply to your product(s) to be exhibited.

※

☐ 1. Hardware solutions	☐ 5. IP core, Macro, Cell libraries	☐ 9. Design data management tool
☐ 2. Hardware development (EDA)	☐ 6. Embedded processor development environments	☐ 10. Mask shop, Foundry
☐ 3. Software solutions	☐ 7. Design service-related (LSI / PCB)	☐ 11. University (R&D), Consortium
☐ 4. IC tester / analyzer	☐ 8. Design infrastructure (WS / PC, Network)	☐ 12. PR-related

Exhibitor Seminars

Refer to Exhibitor Seminars Categories on the reverse side and check the category to be expected with the number of applied sessions.
Fill the total number of applied sessions and the total usage fee in the blanks.
＊may slightly change due to the number of applications.

Categories	Number of sessions	Categories	Number of sessions
☐ A : ESL	sessions	☐ J : SIP	sessions
☐ B : Low Power	sessions	☐ K : DFT	sessions
☐ C : Timing convergence	sessions	☐ L : Physical verification	sessions
☐ D : DFM	sessions	☐ M : Physical implementation	sessions
☐ E : Reliability	sessions	☐ N : Design / Verification service	sessions
☐ F : AMS design / verification	sessions	☐ O : Thermal / Fluid analysis	sessions
☐ G : Functional verification	sessions	☐ P : Others	sessions
☐ H : IP	sessions		Please specify
☐ I : PCB	sessions		
Total	sessions	@¥ 52,500	= (消費税込)

Exhibitor Information

This information will appear in printed materials and on the official EDSFair website exactly as written, so please be careful to provide accurate information.
Please print using uppercase and lowercase letters, as appropriate.

※

Company Name (One letter per box, leave box empty for space)				
Head Office Information	Address			
	CEO'S Official Title		CEO´S Name	
Exhibition Supervisor	Address			
	Title / Division		Name	
	TEL		FAX	
	E-mail			
Invoice Address (Not necessary if same as above)	Address			
	Title / Division		Name	
	TEL		FAX	
	E-mail			
URL				

On behalf of my company, I hereby acknowledge that I have read, understood and will comply with the EDSFair 2011 Nov. Exhibition Regulations and herewith apply to exhibit.

※

Person in charge of our exhibit

Company name: _____

Name (please print): _____

Job title: _____

Signature: _____